



Material Content Data Sheet



Sales Product Name		ICE3AR10080CJZ		Issued		19. July 2018		
MA#		MA001147534						
Package		PG-DIP-7-4		Weight*		652.73 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.854	0.59	0.59	5905	5905
leadframe	inorganic material	phosphorus	7723-14-0	0.049	0.01		74	
	non noble metal	zinc	7440-66-6	0.194	0.03		298	
	non noble metal	iron	7439-89-6	3.884	0.60		5951	
wire	non noble metal	copper	7440-50-8	157.726	24.16	24.80	241641	247964
	noble metal	gold	7440-57-5	0.269	0.04	0.04	413	413
	encapsulation	organic material	carbon black	1333-86-4	1.429	0.22		2190
encapsulation	plastics	epoxy resin	-	46.217	7.08		70806	
	inorganic material	silicondioxide	60676-86-0	428.819	65.70	73.00	656965	729961
leadfinish	non noble metal	tin	7440-31-5	6.460	0.99	0.99	9896	9896
plating	noble metal	silver	7440-22-4	1.911	0.29	0.29	2927	2927
glue	plastics	epoxy resin	-	0.287	0.04		440	
	noble metal	silver	7440-22-4	1.628	0.25	0.29	2494	2934
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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